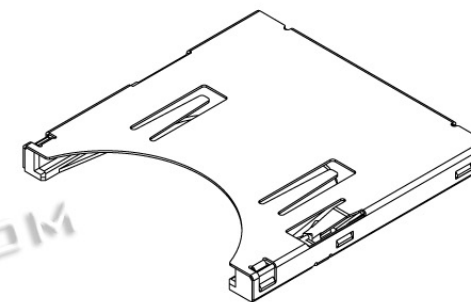
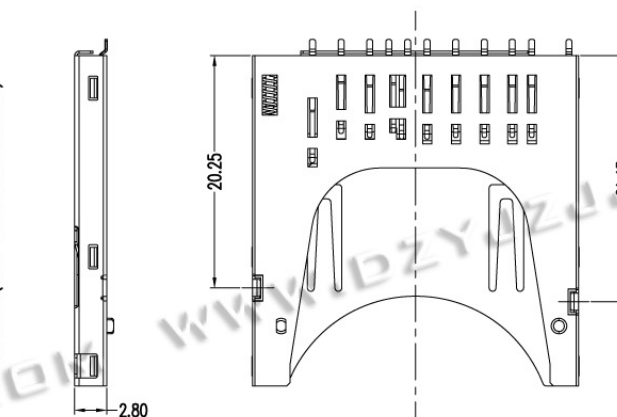




NOTES:

- NOTES:
1. MATERIAL:
 - 1.1 BASE: LCP UL 94V-0, BLACK COLOR.
 - 1.2 CONTACT: COPPER ALLOY.
 - 1.3 SHELL: STAINLESS STEEL.
 - 1.4 SPRING: SWP.
 2. FINISH:

CONTACTS: GOLD PLATED ON CONTACT AREA,
MATTE-TIN ON SOLDER TAIL,
NICKEL UNDERPLATED OVERALL.

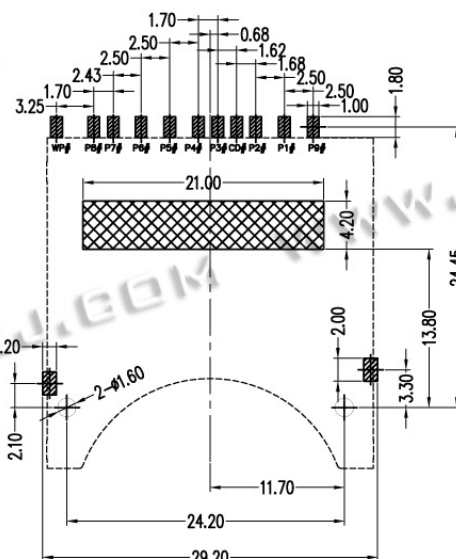
SHELL: NICKEL PLATED.
 3. SPECIFICATION
 - *ELECTRICAL CHARACTERISTICS:

CONTACT CURRENT RATING: 0.5 AMPERES.
DIELECTRIC WITHSTANDING VOLTAGE: AC500V R.M.S.
INSULATION RESISTANCE: 1000 MΩ MINIMUM.
CONTACT RESISTANCE: 100 MΩ MAXIMUM.
 - *ENVIRONMENTAL:

OPERATING TEMPERATURE: -25°C~+85°C.
 - *ENVIRONMENTAL:

MATING CYCLES: 5,000 INSERTIONS.
 - *MECHANICAL CHARACTERISTICS:

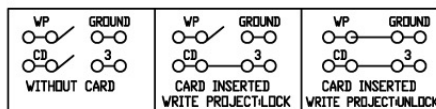
CARD PUSH INSERTION/OUT FORCE: 0.4~1.20KGF.



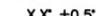
 Pad Area; Keep Out Area

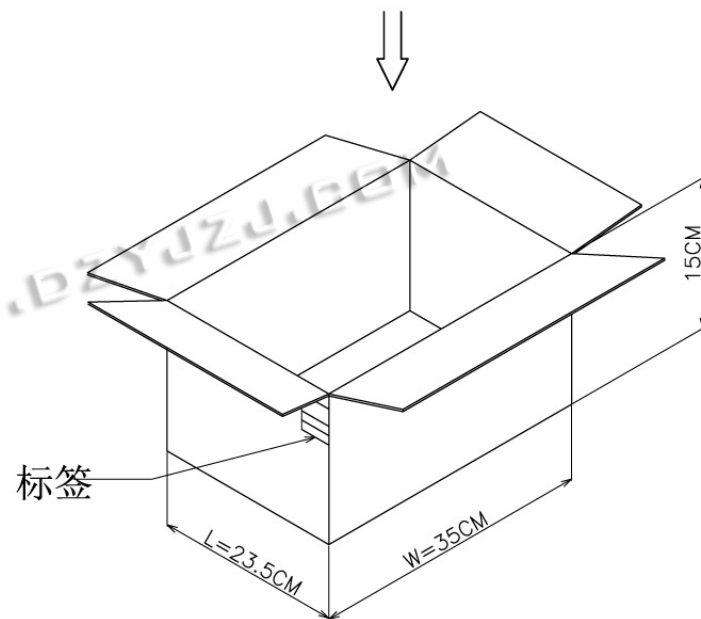
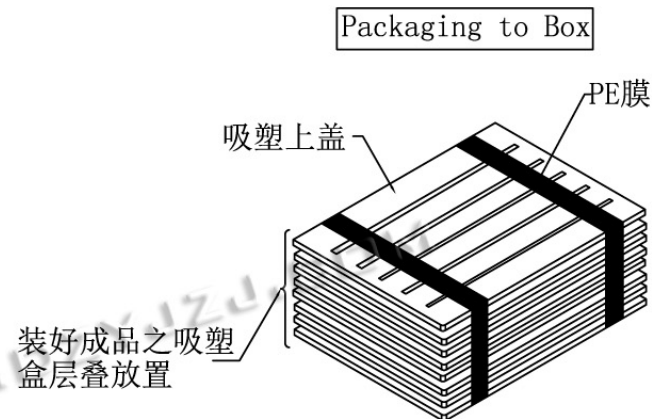
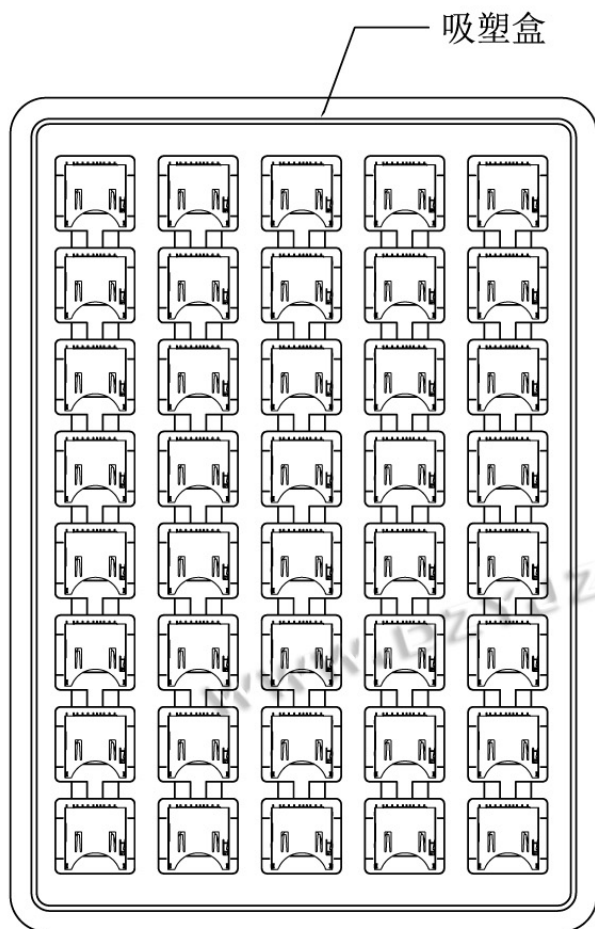
PCB LAYOUT TOP VIEW
(TOLERANCE:±0.05)

SD CARD PIN DESIGN			
Pin#	Name	Type	Card Detect/ Data Line#
1	CD/DAT3	L/O/PP	Command/Response
2	CMD	PP	Supply voltage
3	Vss1	S	Supply voltage ground
4	VDD	S	Supply voltage
5	CLK	I	Clock
6	Vss2	S	Supply voltage ground
7	DAT0	L/O/PP	Data Line [DH0]
8	DAT1	L/O/PP	Data Line [DH1]
9	DAT2	L/O/PP	Data Line [DH2]



深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X: ±2" X.X ±0.5"				SD 带双压片	
		CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYC39-SD11-280
				MOLD NO.	
UNIT: mm [inch]		APPROVED BY: 邱国夷	DATE : 2014-02-23	DRAW NO:	HYC-SD16081610
SCALE: 1:1	SIZE: A4			SHEET NO.	1 OF 1



1. 材质要求:

1.1 纸箱材质:A=B; 尺寸:35*23.5*15 CM;

2. 包装要求:

2.1 将装好产品的吸塑盒重叠叠起, 用PE膜缠绕好捆成一捆, 按统一方向放入纸箱, 并在纸箱内放置干燥剂

2.2 把包装好的成品用胶纸打包封箱, 并在纸箱外贴上标签

3. 包装数量: 25盘 x 40PCS/盘 = 1000 PCS/箱



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 包装图	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱国夷	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	
			SHEET NO.	1 OF 1